

MECHANICAL CASE OUTLINE

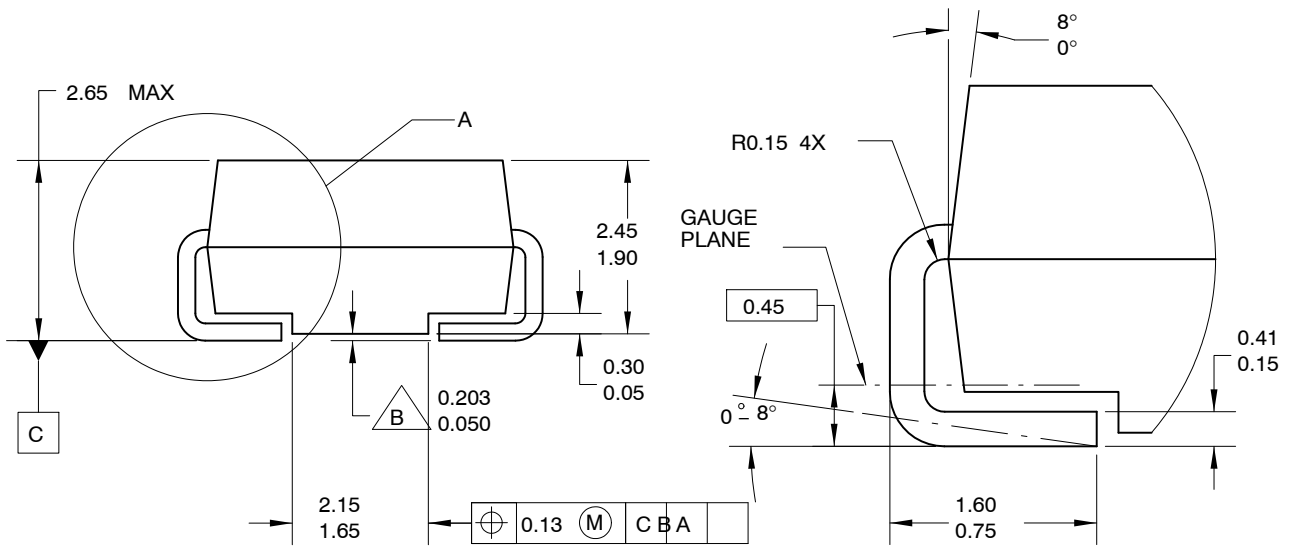
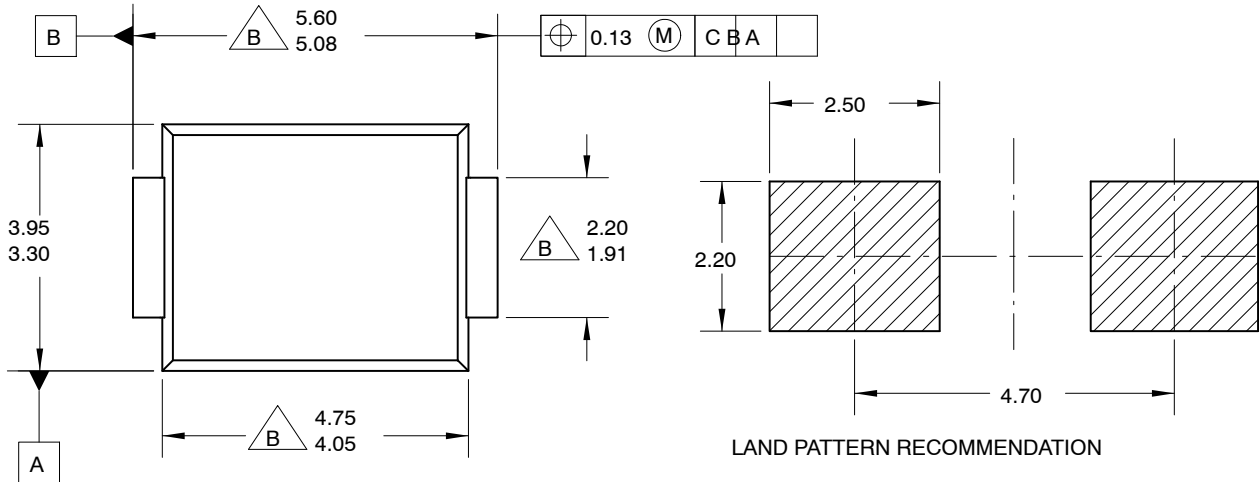
PACKAGE DIMENSIONS

ON Semiconductor®



SMB CASE 403AF ISSUE O

DATE 31 AUG 2016



DETAIL A
SCALE 20 : 1

NOTES:

- A. EXCEPT WHERE NOTED CONFORMS TO JEDEC DO214 VARIATION AA.
- B. DOES NOT COMPLY JEDEC STD. VALUE.
- C. ALL DIMENSIONS ARE IN MILLIMETERS.
- D. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR PROTRUSIONS.
- E. DIMENSION AND TOLERANCE AS PER ASME Y14.5-1994.
- F. LAND PATTERN STD. DIOM5336X240M.

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